

INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Printed boards design, manufacture and assembly – Vocabulary –
Part 1: Common usage in printed board and electronic assembly technologies**

**Conception, fabrication et assemblage de cartes imprimées – Vocabulaire –
Partie 1: Usage commun des techniques d'assemblage des composants
électroniques et des cartes imprimées**



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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**PRINTED BOARDS DESIGN, MANUFACTURE AND ASSEMBLY –
VOCABULARY –****Part 1: Common usage in printed board
and electronic assembly technologies**

FOREWORD

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International Standard IEC 60194-1 has been prepared by IEC technical committee 91: Electronics assembly technology.

This document, together with IEC 60194-2:2017, cancel and replace IEC 60194:2015. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) exclusion of 32 general terms better served by other TCs;
- b) exclusion of 47 terms no longer used by the electronic assembly industry;
- c) inclusion of 14 new terms related with device embedded substrate technology;
- d) inclusion of 113 synonymous terms;
- e) removal of identification codes for terms and annexes.

The text of this International Standard is based on the following documents:

FDIS	Report on voting
91/1688/FDIS	91/1705/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 60194 series, published under the general title *Printed boards design, manufacture and assembly – Vocabulary*, can be found on the IEC website.

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INTRODUCTION

The committee decided to split the revision of IEC 60194:2015 into two separate documents: IEC 60194-1 and IEC 60194-2. This document is the first part of the revision (IEC 60194-1). It is composed of terms and definitions closely related with TC 91 technology.